

Multi Chip Package (MCP)

Ultimate Solution for the Smart Mobile Life

Mobile Memory Solutions from a Memory Market Leader

Optimized to ever-evolving mobile environments, our mobile memory solutions instill the best of SK hynix's technology and market leadership, built over years of close collaboration and shared growth with our customers.

What trends are driving today's mobile market?



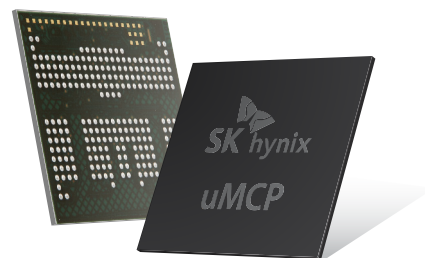
What's in our Multi Chip Package (MCP) lineup?

| A wide range of products for Mobile applications

- DRAM: LPDDR5, LPDDR4X, LPDDR4 etc
- NAND: UFS3.1, UFS2.2, eMMC5.1 etc

| uMCP

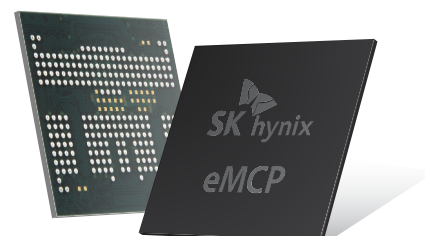
- UFS NAND and LPDDR DRAM stacked in a single package
- Competitively thin form factor packing high densities with smaller footprint



Density (NAND+DRAM)	128~512GB+6~12GB	64~256GB+3~12GB
Speed	6400Mbps	4266Mbps
PKG	297Ball	254Ball

| eMCP

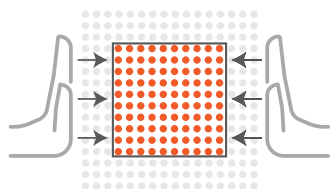
- eMMC NAND and LPDDR DRAM stacked in a single package
- Realizes 40% better space efficiency for mobile devices



Density (NAND+DRAM)	16~128GB+2~6GB
Speed	3733Mbps~4266Mbps
PKG	254Ball

What makes our mobile solutions competitive?

A trusted memory provider with 30+ years of experience, SK hynix closely collaborates with global brands to offer advanced mobile memory solutions that are tailored to the market's needs for slimmer, faster, and more reliable mobile devices.



Ultra-slim, compact package for mobile devices

Small and slim package saving up to 40% of space



World-leading technology and performance

Advanced performance enabled by cutting-edge 1nm DRAM and 128-layer 4D NAND Flash memory



Continuous product quality control

Stable quality supported by continuous sequentiality and customer service improvement efforts